

# Global Low-warpage Epoxy Molding Compounds Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

<https://marketpublishers.com/r/G0EA220095B9EN.html>

Date: July 2026

Pages: 125

Price: US\$ 3,480.00 (Single User License)

ID: G0EA220095B9EN

## Abstracts

According to our (Global Info Research) latest study, the global Low-warpage Epoxy Molding Compounds market size was valued at US\$ 741 million in 2025 and is forecast to a readjusted size of US\$ 1549 million by 2032 with a CAGR of 10.5% during review period.

Low warpage epoxy molding compound is a thermosetting composite encapsulation material used in semiconductor packaging, typically formulated with epoxy resin, phenolic curing agents, spherical silica filler, coupling agents, release agents, low stress modifiers, flame retardant systems and functional additives, focusing on reducing thermal stress and package warpage during chip encapsulation, substrate packaging, wafer level packaging, and power device packaging. Main product forms include granular, powder, and liquid molding compounds as well as molded underfill materials, with core processes covering resin formulation design, surface treatment of inorganic fillers, high filler compounding, low ionic contamination control, granulation, curing reaction control, and reliability validation. Key performance parameters include low coefficient of thermal expansion, low modulus, low shrinkage, high flowability, strong adhesion, low moisture absorption, reflow solder resistance, thermal cycling resistance, and high electrical insulation reliability, mainly applied to BGA, CSP, FCBGA, FCCSP, FOWLP, PLP, SiP, automotive power devices, memory devices, and advanced logic chip packaging. In 2025, the global average gross margin of low warpage epoxy molding compound is approximately 28% to 42%, mainstream product prices are around 18,000 to 30,000 US dollars per ton, and high-end specifications for advanced packaging applications range from 22,000 to 35,000 US dollars per ton.

Low warpage epoxy molding compound is a high reliability segment within

semiconductor packaging materials. It represents the upgrade of conventional epoxy molding compounds toward advanced packaging, thinner packages, larger die sizes and higher reliability power devices. The upstream supply chain mainly includes epoxy resin, phenolic curing agents, spherical silica fillers, flame retardants, low stress modifiers and electronic grade additives. The midstream section is centered on formulation design, compounding, granulation, clean manufacturing and reliability testing. Downstream demand is mainly driven by advanced logic devices, memory packages, automotive power devices, system in package, fan out wafer level packaging and panel level packaging. As package structures become thinner and more complex, warpage control has become a critical factor affecting process yield, solder joint reliability and long term package stability.

The competitive landscape remains highly concentrated. High end products are still led by established Japanese and Korean material platforms, while manufacturers in mainland China and Taiwan are accelerating localization and import substitution. Customer qualification in semiconductor packaging is strict and time consuming, so the barrier to entry is not limited to formulation know how. It also depends on stable mass production, impurity control, failure analysis capability, application engineering support and long term customer validation. In recent years, Chinese suppliers have improved their position through capacity expansion, acquisition, process upgrades and closer cooperation with domestic packaging houses, but there is still a gap in extremely low warpage materials, large area advanced packaging, molded underfill and high end automotive grade applications.

Industry policy, supply chain security and regional semiconductor investment are reshaping the supply structure. Growth is being supported by advanced packaging, AI chips, high bandwidth memory, automotive electronics and power semiconductor expansion. Future demand will be driven more by performance upgrading than by volume growth alone. Product development will focus on lower coefficient of thermal expansion, lower modulus, higher filler loading, better flowability, lower ionic contamination, stronger thermal cycling resistance and higher package yield. Overall, this is a high growth niche within a mature material system. The outlook is positive, but qualification cycles, fast technology migration and uncertainty in high end capacity ramp up remain the key constraints.

This report is a detailed and comprehensive analysis for global Low-warpage Epoxy Molding Compounds market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Form and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as

well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

#### Key Features:

Global Low-warpage Epoxy Molding Compounds market size and forecasts, in consumption value (\$ Million), sales quantity (Ton), and average selling prices (US\$/Ton), 2021-2032

Global Low-warpage Epoxy Molding Compounds market size and forecasts by region and country, in consumption value (\$ Million), sales quantity (Ton), and average selling prices (US\$/Ton), 2021-2032

Global Low-warpage Epoxy Molding Compounds market size and forecasts, by Form and by Application, in consumption value (\$ Million), sales quantity (Ton), and average selling prices (US\$/Ton), 2021-2032

Global Low-warpage Epoxy Molding Compounds market shares of main players, shipments in revenue (\$ Million), sales quantity (Ton), and ASP (US\$/Ton), 2021-2026

#### The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for Low-warpage Epoxy Molding Compounds

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Low-warpage Epoxy Molding Compounds market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Sumitomo Bakelite Co., Ltd., Resonac Corporation, Panasonic Industry Co., Ltd., Shin-Etsu Chemical Co., Ltd., Kyocera Corporation, Nagase ChemteX Corporation, KCC Corporation, Samsung SDI Co., Ltd., Chang Chun Group, Jiangsu HHCK Advanced Materials Co., Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

## Market Segmentation

Low-warpage Epoxy Molding Compounds market is split by Form and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Form, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

### Market segment by Form

Granular Epoxy Molding Compound

Powder Epoxy Molding Compound

Liquid Molding Compound

Others

### Market segment by Resin Matrix Type

Epoxy-based

Polyimide-based

Others

### Market segment by Filler Content

High Filler Content (>85 wt%)

Medium Filler Content (70-85 wt%)

Low Filler Content (

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